

# Multilayer Ceramic Chip Capacitors

▼ more

## CGA6M3X7S2A475K200AB



**TDK item description** ? CGA6M3X7S2A475KT\*\*\*\*

**Applications** Automotive Grade

**Feature** Mid Mid Voltage (100 to 630V)  
AEC-Q200 AEC-Q200

**Series** CGA6(3225) [EIA 1210]

**Status** Production



● ●  
 Images are for reference only and show exemplary products.

PDF file of this page

Contact

### Documents

- Catalog Update
- Specification
- RoHS Certificate
- SVHC/REACH Certificate Update
- Selection Guide for Automotive MLCC New
- [Promotion Video] xEV Higher Withstand Voltage Applications Recommended
- Sample Kits
- Characterization Sheet

### Technical Support Tools

- S-parameter
- SPICE Netlist (Simple)
- SPICE Netlist (Precision)
- Equivalent Circuit Model
- DC Bias/Superimposition Model (HSPICE)

Size	
Length(L)	3.20mm ±0.40mm
Width(W)	2.50mm ±0.30mm
Thickness(T)	2.00mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	
Recommended Land Pattern (PA)	2.00mm to 2.40mm
Recommended Land Pattern (PB)	1.00mm to 1.20mm
Recommended Land Pattern (PC)	1.90mm to 2.50mm

Electrical Characteristics	
Capacitance	4.7μF ±10%
Rated Voltage	100VDC
Temperature Characteristic ?	X7S(±22%)
Dissipation Factor (Max.)	5%
Insulation Resistance (Min.)	106MΩ

Other	
Soldering Method	Reflow
AEC-Q200	Yes
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	1000pcs

**Characteristic Graph** (This is reference data, and does not guarantee the products characteristics.)



CGA6M3X7S2A475K200AB

Configuration

Capacitance

CGA6M3X7S2A475K200AB

Configuration

Temperature Characteristic

CGA6M3X7S2A475K200AB( No Bias) CGA6M3X7S2A475K200AB(DC Bias = 50V )

Configuration

CGA6M3X7S2A475K200AB

Configuration

DC Bias Characteristic

CGA6M3X7S2A475K200AB

Configuration

Ripple Temperature Rising

CGA6M3X7S2A475K200AB(100kHz) CGA6M3X7S2A475K200AB(500kHz) CGA6M3X7S2A475K200AB(1MHz)

Configuration



[Selection Guides](#) [Search by Part No.](#) [Search by Characteristics](#) [Distributor Inventory Check](#) [Cross Reference](#)

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- RF Components and Modules >
- Voltage / Current / Temperature Protection Devices >
- Sensors and Sensor Systems >
- Ceramic Switching / Heating, Piezo Components, Buzzers and Microphones >
- Transformers >

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